



Heraeus

Technical Data Sheet

Solder Paste F381 Series

Description	The F 381 series of solder pastes comprise a ready-to-use homogeneous mixture with low odour characteristics, consisting of metal powder, binders, solvents, fluxes and thixotropic agents. Equipped with a covalently-bonded halogen flux chemistry, the pastes confer outstanding wetting that is ideal for applications requiring difficult-to-solder surfaces.										
Key Benefits	<ul style="list-style-type: none"> - Outstanding wetting - Excellent printing properties - Very high green strength 			Compliant Products							
Product Code and Alloy	Code		Powder Properties			Application					
	Paste	Alloy	Metal Content	Viscosity	Powder Type	Particle Size	Alloy	Melting Point	Stencil Printing	Screen Printing	Dispensing
	F381	Sn63	90	M	4	20 - 38 µm	Sn63/Pb37	183°C	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
	F381	Sn62	90,5	M	3	25 - 45 µm	Sn62/Pb36/Ag2	179°C	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
Flux Activity	No Clean		Water Washable		ISO 9454-1:1990 [DIN EN 29454-1:1993]	J-STD-004A:2004		Belcore GR-78-Core [Issue 1:1997]	Siemens Norm [SN 59650:1998]		
	<input checked="" type="checkbox"/>		<input type="checkbox"/>		1.2.2.C	REM1		not tested	not tested		
Halogen Content	Halogen Free <input type="checkbox"/>					Halogen Zero - No Halogen added in the Flux: <input type="checkbox"/>					
	Halogen Free-Tolerances from IEC 61249-2-21: Cl or Br <900ppm, total <1500ppm; measured according to BS EN 14582					Halogen Zero - Tolerance: Halogen < 50 ppm; measured according to BS EN 14582					
Paste Conditioning	Remove paste from fridge: Before opening the package leave paste 2 hours at room temperature so that paste warms up. Do not open jar/cartridge while paste is cold to prevent condensation of moisture on the paste - this causes defects, e.g. solder balling etc. Do not heat the paste. Before use of paste jar: To obtain uniform, stable viscosity stir paste for 1 to 2 min, using stainless steel or chemically resistive plastic spatula.										
Reflow	Temperature profile adjustment according IPC/JEDEC J-STD-020.										
Cleaning	After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.										
Storage	Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity. Max expiration date : please refer to the expiry date on the label of the packaged product. Storage conditions in the refrigerator at 2-10°C.										
Contact	www.heraeus-contactmaterials.com					Version	TDS_Solder Paste F381 Series_18.March 2015				

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